



**Data Sheet Issue: 1** 

# **Thyristor/Diode Modules M##220**

Absolute	Maximum	Ratings

Vrrm Vdrm [V]			
	MCC	MCD	MDC
2800	220-28io3	220-28io3	220-28io3

	VOLTAGE RATINGS	MAXIMUM LIMITS	UNITS
Vdrm	Repetitive peak off-state voltage <sup>1)</sup>	2800	V
V <sub>DSM</sub>	Non-repetitive peak off-state voltage 1)	2900	V
Vrrm	Repetitive peak reverse voltage <sup>1)</sup>	2800	V
Vrsm	Non-repetitive peak reverse voltage <sup>1)</sup>	2900	V

	OTHER RATINGS	MAXIMUM LIMITS	UNITS
I <sub>T(AV)M</sub>	Maximum average on-state current, $T_c = 85^{\circ}C^{2}$	235	А
Ιτ(Αν)Μ	Maximum average on-state current. $T_c = 100^{\circ}C^{2}$	165	А
IT(RMS)M	Nominal RMS on-state current, $T_c = 55^{\circ}C^{2}$	543	А
I <sub>T(d.c.)</sub>	D.C. on-state current, $T_C = 55^{\circ}C$	455	А
I <sub>TSM</sub>	Peak non-repetitive surge $t_p = 10 \text{ ms}$ , $V_{RM} = 60\% V_{RRM}$ <sup>3)</sup>	5.00	kA
I <sub>TSM2</sub>	Peak non-repetitive surge $t_p$ = 10 ms, $V_{RM} \le 10V^{-3}$	5.50	kA
l²t	$I^{2}t$ capacity for fusing $t_{p} = 10$ ms, $V_{RM} = 60\% V_{RRM}$ <sup>3)</sup>	125	kA²s
l²t	$I^2t$ capacity for fusing $t_p$ = 10 ms, $V_{RM} \le$ 10 V $^{3)}$	150	kA²s
( 1: / 14)	Critical rate of rise of on-state current (repetitive) 4)	100	• /
(di/dt) <sub>cr</sub>	Critical rate of rise of on-state current (non-repetitive) 4)	200	A/µs
Vrgm	Peak reverse gate voltage	5	V
Р <sub>GM</sub>	Peak forward gate power	3	W
VISOL	Isolation Voltage 5)	3000	V
T <sub>vj op</sub>	Operating temperature range	-40 to +125	°C
T <sub>stg</sub>	Storage temperature range	-40 to +125	°C

Notes:

1) De-rating factor of 0.13% per °C is applicable for  $T_{vj}$  below 25°C.

2) Single phase; 50 Hz, 180° half-sinewave.

3) Half-sinewave,  $125^{\circ}C T_{vj}$  initial.

4)  $V_D = 67\% V_{DRM}$ ,  $I_{FG} = 2 \text{ A}$ ,  $di_g/dt = 1 \text{ A}/\mu \text{s}$ ,  $T_C = 125^{\circ}\text{C}$ .

5) AC RMS voltage, 50 Hz, 1min test

## **Characteristics**

	PARAMETER	MIN.	TYP.	MAX.	TEST CONDITIONS <sup>1)</sup>	UNITS
Vtm	Maximum peak on-state voltage	-	-	2.00	I⊤M = 785 A, T <sub>VJ</sub> = 25°C	V
V <sub>T0</sub>	Threshold voltage	-	-	0.90		V
r⊤	Slope resistance	-	-	1.10		mΩ
(dv/dt) <sub>cr</sub>	Critical rate of rise of off-state voltage	-	-	1000	V <sub>D</sub> = 80% V <sub>DRM</sub> , linear ramp, Gate o/c	V/µs
Idrm	Peak off-state current	-	-	50	Rated V <sub>DRM</sub>	mA
Irrm	Peak reverse current	-	-	50	Rated V <sub>RRM</sub>	mA
V <sub>GT</sub>	Gate trigger voltage	-	2.0	-		V
lgт	Gate trigger current	-	150	-	$T_{vj} = 25^{\circ}C, V_{D} = 12 V, I_{T} = 3 A$	mA
Vgd	Gate non-trigger voltage	-	0.25	-	67% Vdrm	V
۱L	Latching current	-	-	700	V <sub>D</sub> = 12 V, T <sub>vj</sub> = 25°C	mA
Ін	Holding current	-	-	300	$V_D = 12 V, T_{vj} = 25^{\circ}C$	mA
t <sub>gd</sub>	Gate controlled turn-on delay time	-	-	3.00	I <sub>FG</sub> = 2 A, t <sub>r</sub> = 50 μs, V <sub>D</sub> = 40%V <sub>DRM</sub> , I <sub>TM</sub> = I <sub>TAV</sub> , di/dt = 1A/μs, T <sub>vj</sub> = 25°C	μs
tq	Turn-off time	-	-	200	$I_{TM}$ = 235A, t <sub>p</sub> = 1 ms, di/dt = 10 A/µs, V <sub>R</sub> = 100 V, V <sub>DR</sub> = 67%V <sub>DRM</sub> , dv <sub>DR</sub> /dt = 50 V/µs	μs
L		-	0.1100	-	Single Arm	K/W
RthJC	Thermal resistance, junction to case	-	0.0550	-	Whole Module	K/W
<b>D</b>	<b>T</b> he manual manufacture of the statistic	-	0.040	-	Single Arm	K/W
RthCH	Thermal resistance, case to heatsink	-	0.020	-	Whole Module	K/W
F1	Mounting force (to heatsink)	-	6.00	-		Nm
F <sub>2</sub>	Mounting force (to terminals)	-	9.00	-	2)	Nm
Wt	Weight	-	800	-		g

Notes:

1) Unless otherwise indicated  $T_{vj}$ =125°C. 2) Screws must be lubricated.

## **Notes on Ratings and Characteristics**

#### 1.0 Voltage Grade Table

Voltage Grade	Voltage Grade V <sub>DRM</sub> V <sub>RRM</sub> V		V <sub>D</sub> V <sub>R</sub> DC V	
28	2800	2900	1650	

## 2.0 Extension of Voltage Grades

This report is applicable to other voltage grades when supply has been agreed by Sales/Production.

## 3.0 De-rating Factor

A blocking voltage de-rating factor of 0.13%/°C is applicable to this device for T<sub>vj</sub> below 25°C.

## 4.0 Repetitive dv/dt

Standard dv/dt is 1000V/µs.

## 5.0 Snubber Components

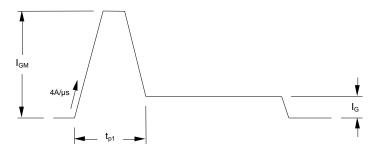
When selecting snubber components, care must be taken not to use excessively large values of snubber capacitor or excessively small values of snubber resistor. Such excessive component values may lead to device damage due to the large resultant values of snubber discharge current. If required, please consult the factory for assistance.

## 6.0 Rate of rise of on-state current

The maximum un-primed rate of rise of on-state current must not exceed 400A/µs at any time during turnon on a non-repetitive basis. For repetitive performance, the on-state rate of rise of current must not exceed 200A/µs at any time during turn-on. Note that these values of rate of rise of current apply to the total device current including that from any local snubber network.

## 7.0 Gate Drive

The nominal requirement for a typical gate drive is illustrated below. An open circuit voltage of at least 30V is assumed. This gate drive must be applied when using the full di/dt capability of the device.



The magnitude of  $I_{GM}$  should be between five and ten times  $I_{GT}$ , which is shown on page 2. Its duration  $(t_{p1})$  should be 20µs or sufficient to allow the anode current to reach ten times  $I_L$ , whichever is greater. Otherwise, an increase in pulse current could be needed to supply the necessary charge to trigger. The 'back-porch' current  $I_G$  should remain flowing for the same duration as the anode current and have a magnitude in the order of 1.5 times  $I_{GT}$ .

 $W_{AV} = \frac{\Delta T}{R_{th}}$  $\Delta T = T_{j \max} - T_C$ 

# 8.0 Computer Modelling Parameters

## 8.1 Thyristor Dissipation Calculations

$$I_{AV} = \frac{-V_{T0} + \sqrt{V_{T0}^{2} + 4 \cdot ff^{2} \cdot r_{T} \cdot W_{AV}}}{2 \cdot ff^{2} \cdot r_{T}}$$

Where  $V_{T0}$  = 0.9 V,  $r_T$  = 1.10 m  $\Omega.$ 

 $R_{th}$  = Supplementary thermal impedance, see table below and

ff = Form factor, see table below.

Supplementary Thermal Impedance								
Conduction Angle	30°	60°	90°	120°	180°	270°	d.c.	
Square wave	3.46	2.45	2	1.73	1.41	1.15	1	
Sine wave	3.98	2.78	2.22	1.88	1.57			

and:

Form Factors							
Conduction Angle	30°	60°	90°	120°	180°	270°	d.c.
Square wave	3.464	2.449	2	1.732	1.414	1.149	1
Sine wave	3.98	2.778	2.22	1.879	1.57		

8.2 D.C. Thermal Impedance Calculation

$$r_t = \sum_{p=1}^{p=n} r_p \cdot \left(1 - e^{\frac{-t}{\tau_p}}\right)$$

Where p = 1 to *n* and:

- n = number of terms in the series
- t = Duration of heating pulse in seconds
- $r_t$  = Thermal resistance at time t
- $r_p$  = Amplitude of  $p_{th}$  term
- $\tau_p$  = Time Constant of r<sub>th</sub> term

The coefficients for this device are shown in the table below:

D.C.								
Term	1	2	3	4	5	6		
rp	0.1293	0.01314	0.02771	-0.05535	0.0528	0.002749		
τρ	2.823	1.393	0.3322	0.0611	0.05731	0.002713		

## **Outline Drawing & Ordering Information**

